ASSOCIATION CONNECTING ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	IPC. Bannockl	ourn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	ibstances v s all lower	within the manufacture level materials for v	urer listed which the	item. Note: i manufacture	f the item is an as r has engineering	ssembly with low responsibility.	
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					ion				
Supplier Information														
Company name* Company			pany unique ID			Unique ID Authority				Respor	Response Date*			
onsemi									2025-0	2025-05-12				
ntact Name Title - Contact					Phone - Contact*				Email	Email - Contact*				
Product-Env-Stewards Product Env			Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			sentative			Phone - Representative*				Email ·	Email - Representative*			
Product-Env-Stewards Prod			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item Numl		Number Mfr Item Name			Effective Date Version Manufacturing Sit		Ianufacturing Site		Weight*	UOM	Unit Type		
	FDBL94	DBL9406-F085 NMOS TOLL 40V		V 1.8 mOhm		2025-05-12	05-12 PBB		BB		811.7391	mg	Each	
Ianufacturing Proccess Informa	ntion		·											
Terminal Plating / Grid Array M	laterial 7	ial Terminal Base Alloy		J-STD-020 MSI	L Rating	Peak Proc	Process Body Temperature Max Time at Peak		k Tempera	ture Numb	per of Reflow Cyc	cles		
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	seco	nds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	ldering is 10-3	0 seconds											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	6.35	mg	Supplier	Silicon (Si)	7440-21-3		6.35	mg	
Die Attach Solder	7.6901	mg	Supplier	Silver (Ag)	7440-22-4		0.1923	mg	
			А	Lead (Pb)	7439-92-1	7a	7.344	mg	
			Supplier	Tin (Sn)	7440-31-5		0.1538	mg	
Lead Frame	474.555	mg	В	Nickel (Ni)	7440-02-0		0.2373	mg	
			Supplier	Iron (Fe)	7439-89-6		0.4746	mg	
			Supplier	Copper (Cu)	7440-50-8		473.7008	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.1424	mg	
Mold Compound-Black	314.85	mg		Epoxy resin	proprietary data		41.875	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.6297	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		272.3452	mg	
Plating	8.12	mg	Supplier	Tin (Sn)	7440-31-5		8.12	mg	
Wire Bond - Al	0.174	mg	Supplier	Aluminum (Al)	7429-90-5		0.174	mg	